

ABSTRACT

A printed circuit board comprises a base substrate and an external interconnection terminal provided on the base substrate, wherein external interconnection terminal comprises a land formed on a front surface of the base substrate and a metal plate soldered upon the land via a solder layer, a through-hole being formed in the base substrate such that the through-hole penetrates through the land and through the base substrate, the through-hole being filled with a solder such that the solder in the through-hole extends in continuation to the solder layer connecting the metal plate to the land.